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Part Number:

73644-3203

Status:

Active

Overview:

HDM®

Description:

2.00mm Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position B, 144 Circuits

Documents:

3D Model

RoHS Certificate of Compliance (PDF)

Drawing (PDF)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73644

Application

Backplane

Comments

Standard Press-Fit, Tin/Lead (SnPb)

Component Type

PCB Header

Overview

HDM®

Product Name

HDM®

Style

N/A

UPC

800754799607

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

Yes

Keying to Mating Part

Yes

Material - Metal

Phosphor Bronze, Stainless Steel

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Net Weight

9.729/g

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

3.50mm

PCB Locator

No

PCB Retention

Yes

PCB Thickness - Recommended

2.50mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Pitch - Termination Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

0.381µm

Polarized to PCB

No

Stackable

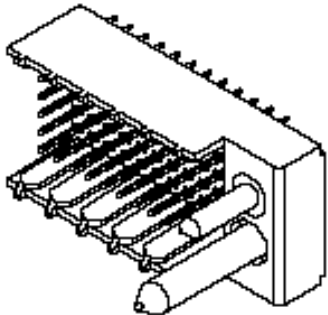
No

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55°C to +105°C



Series

image - Reference only

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Low-Halogen Status

Low-Halogen

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
73644Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | [FAQ](#)
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	
Flat Rock Tooling for	0622013700
Pneumatic Press	

Termination Interface: Style

Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact

1A

Data Rate

1.0 Gbps

Real Signals (per 25mm)

75

Shielded

No

Voltage - Maximum

250V AC

Material Info

Reference - Drawing Numbers

Sales Drawing

SDA-73644-****

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